

## **Abstract**

# **Bump Bonding at JPL's MicroDevices Laboratory**

**So Cal 99 presentation by Mike Fitzsimmons**

Bump bonding is an increasingly important method of interconnecting sensors and their associated readout electronics. An overview of the bump bonding capabilities at JPL's Microdevices Laboratory and examples of working hybrids will be presented. Details specific to indium bump bonding of already diced chips shall be given to assist those who might be planning such projects. Topics requiring further investigation prior to flight qualification of bump bonded parts will also be discussed.